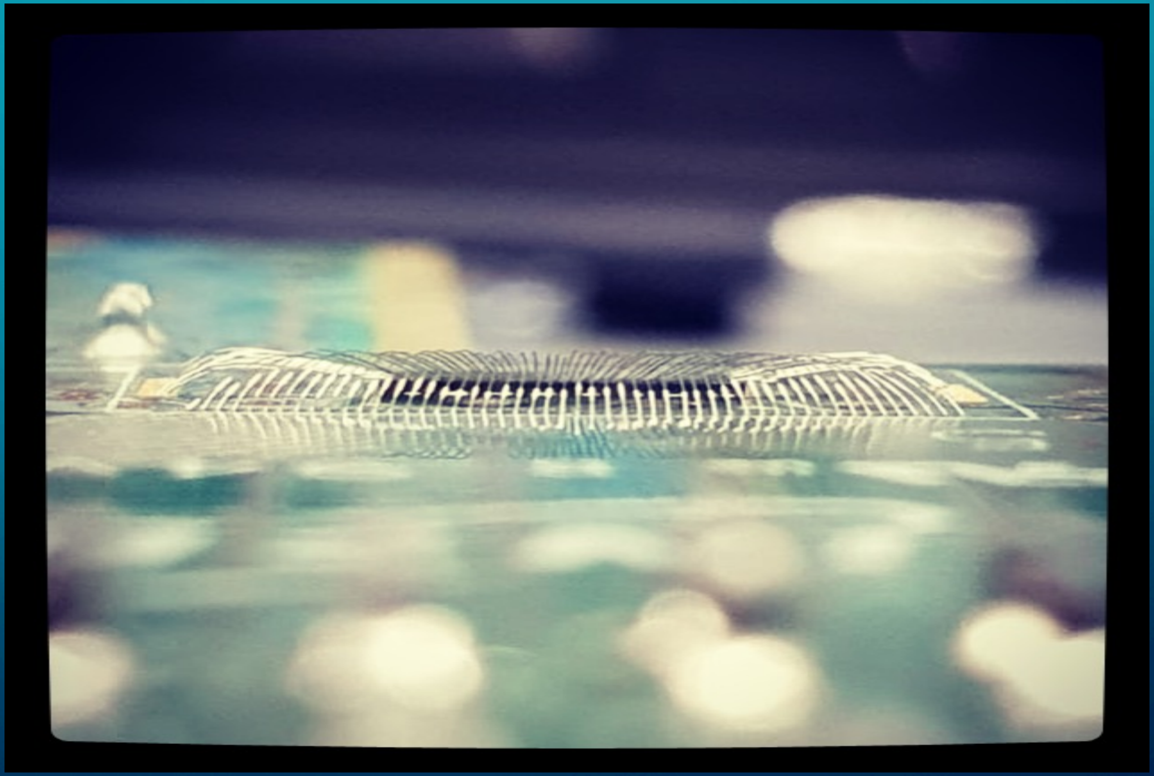
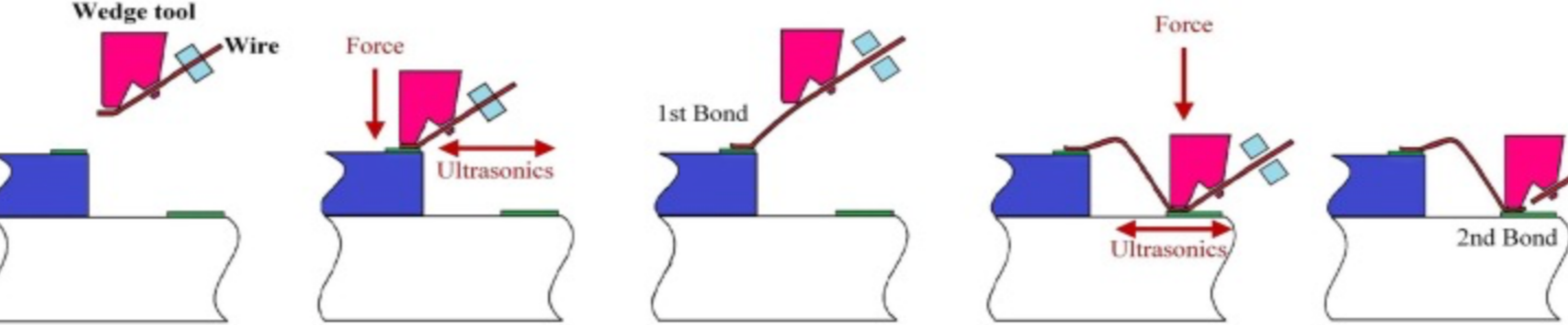
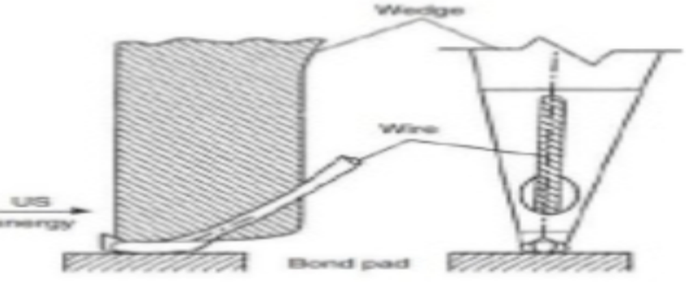
WEDGE WIRE BONDING (MICRO SALDATURA AD ULTRASUONO)

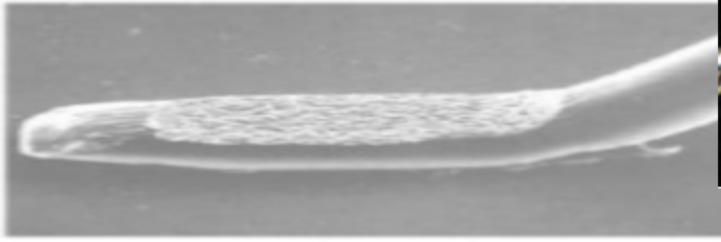
- E’ una saldatura che usa l’ultra suono per fare le saldature con filo di aluminio (1% Si) da 25 o 17 micron. Questo e’ il sistema piu’ usato per i semicondutori.



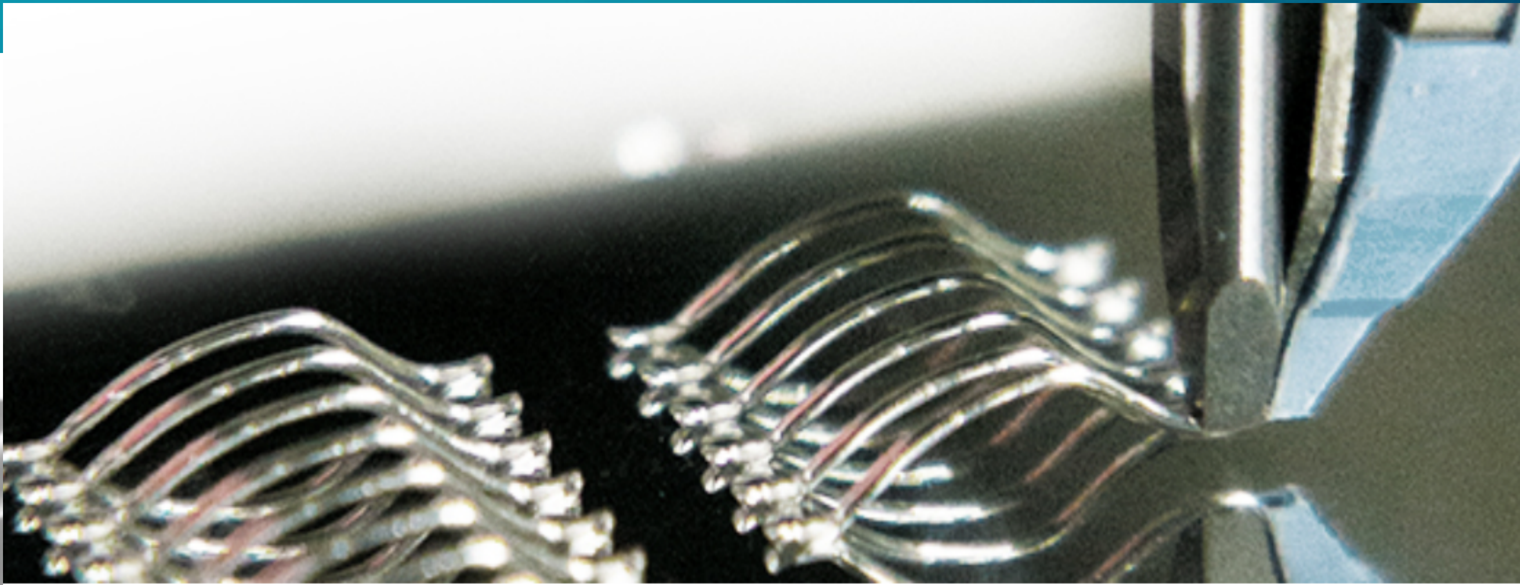
ULTRASONIC BONDING





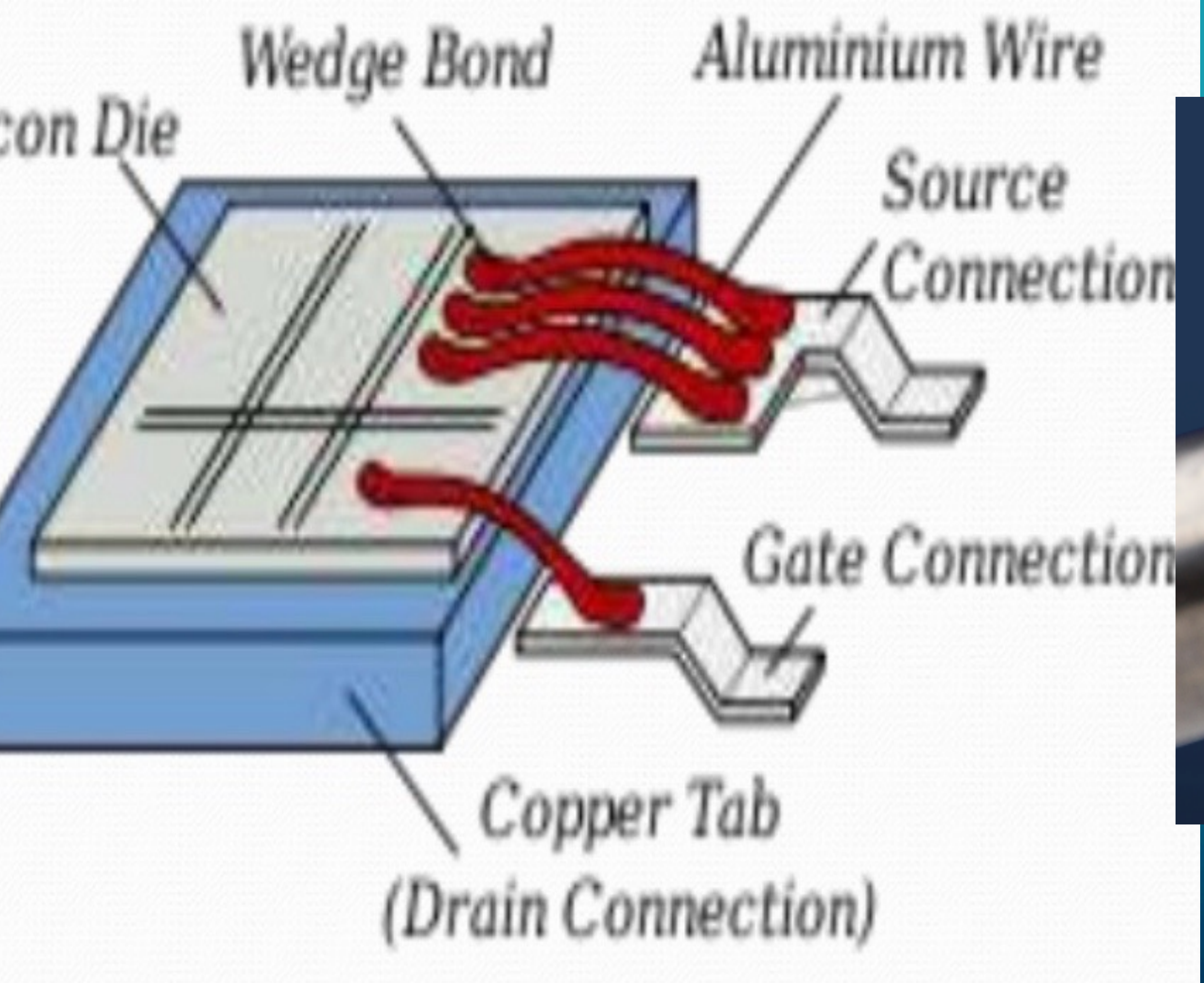


Wedge bond



MACCHINA DA BONDING K&S

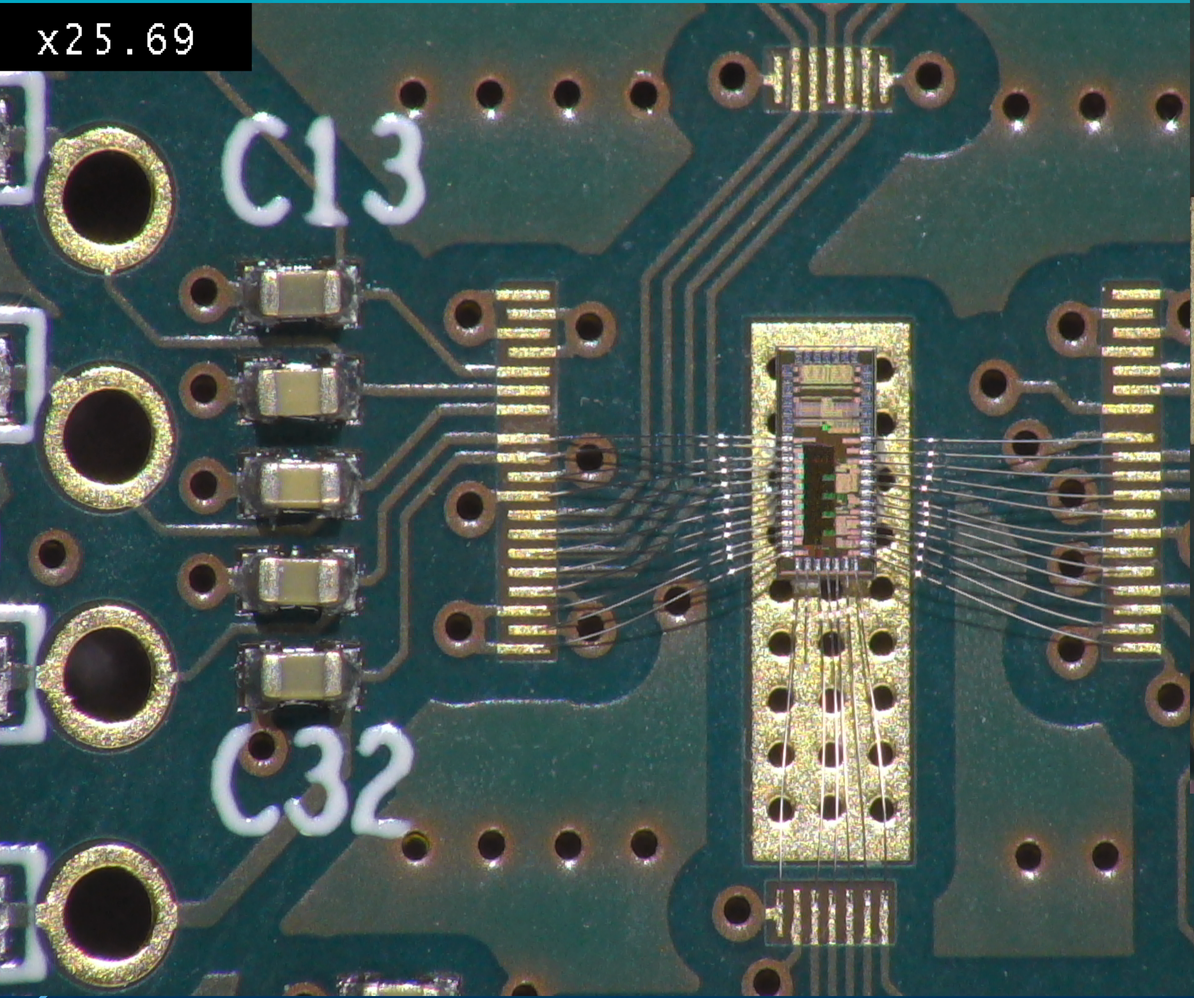
BONDING & TOOL

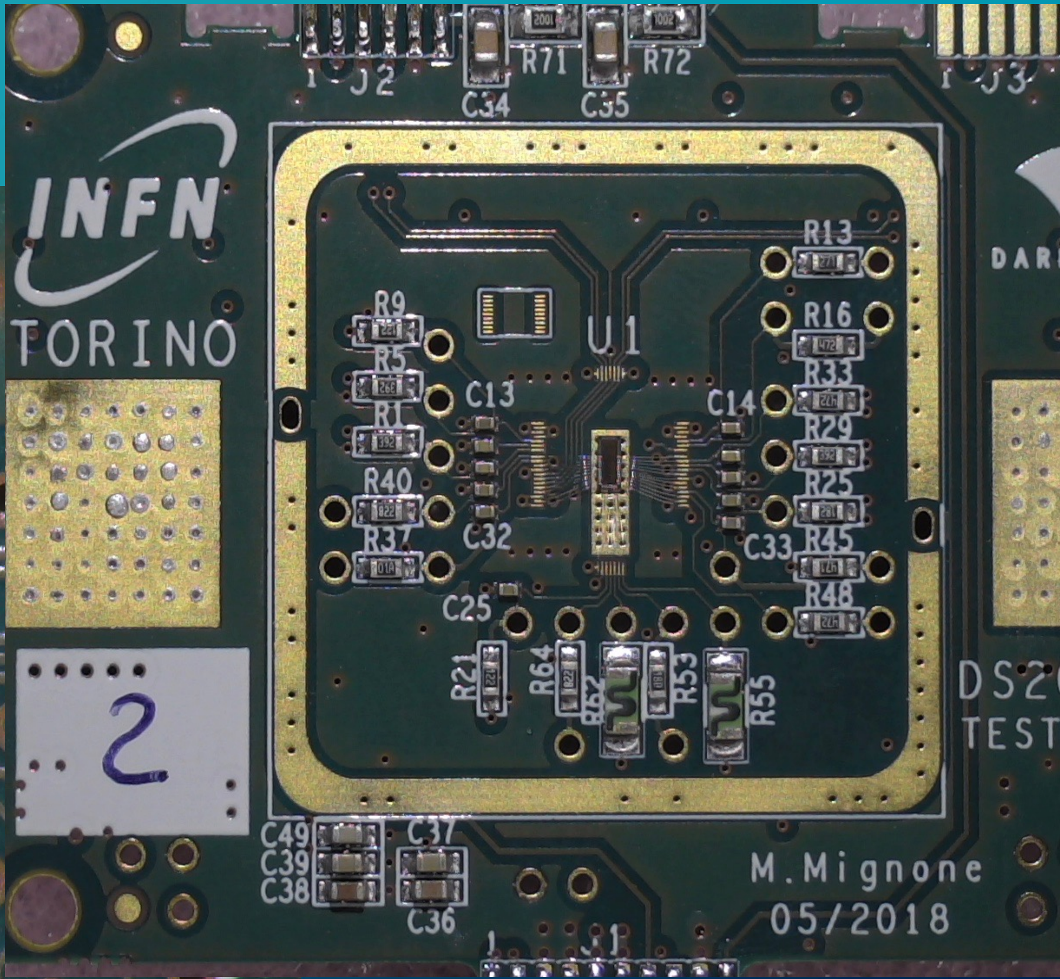


DARKSIDE

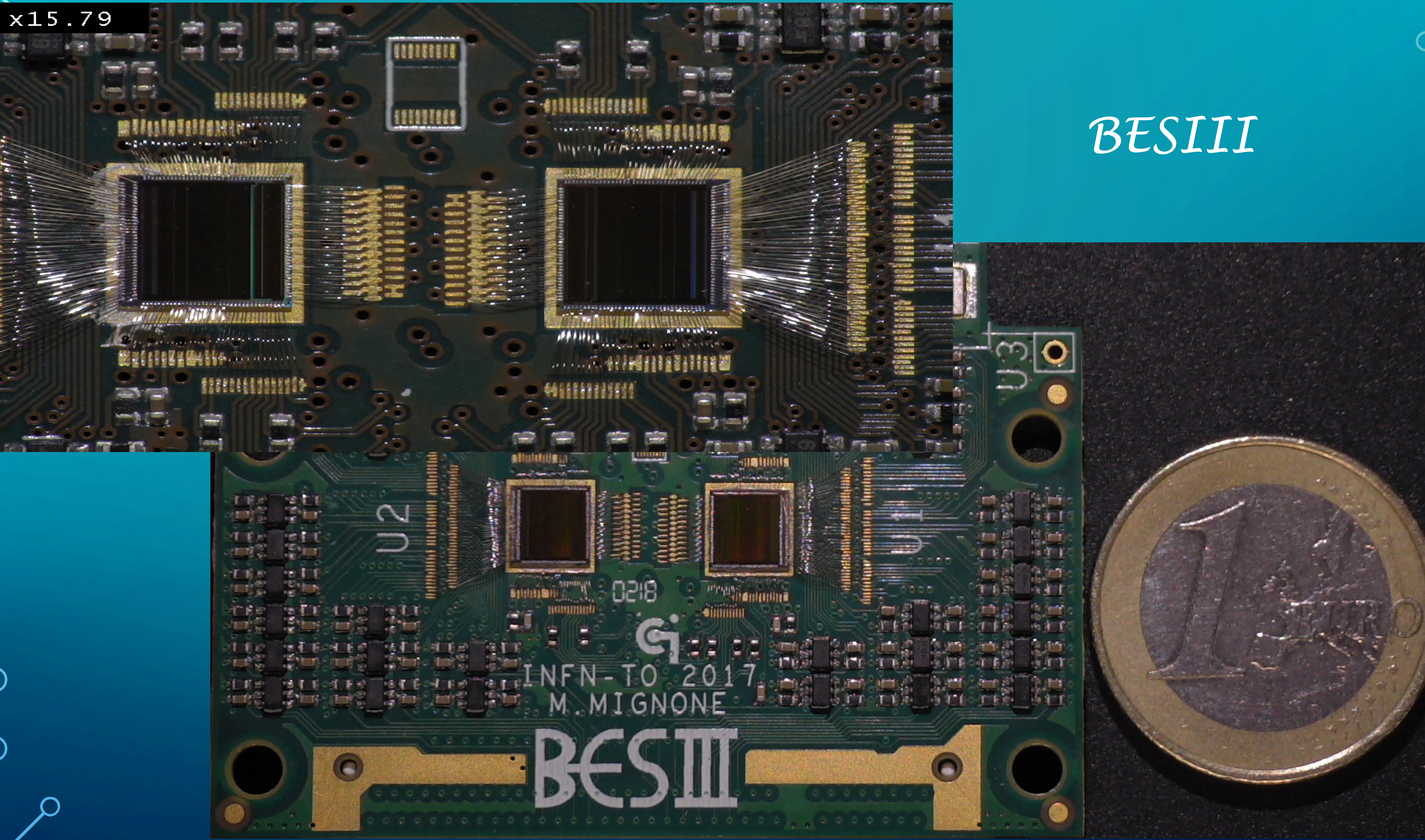
rimento del Gran Sasso per la
rca della materia oscura.

mo è un chip di test chiamato
KTC1 utilizzato per studiare
e l'elettronica si comporta a
°C



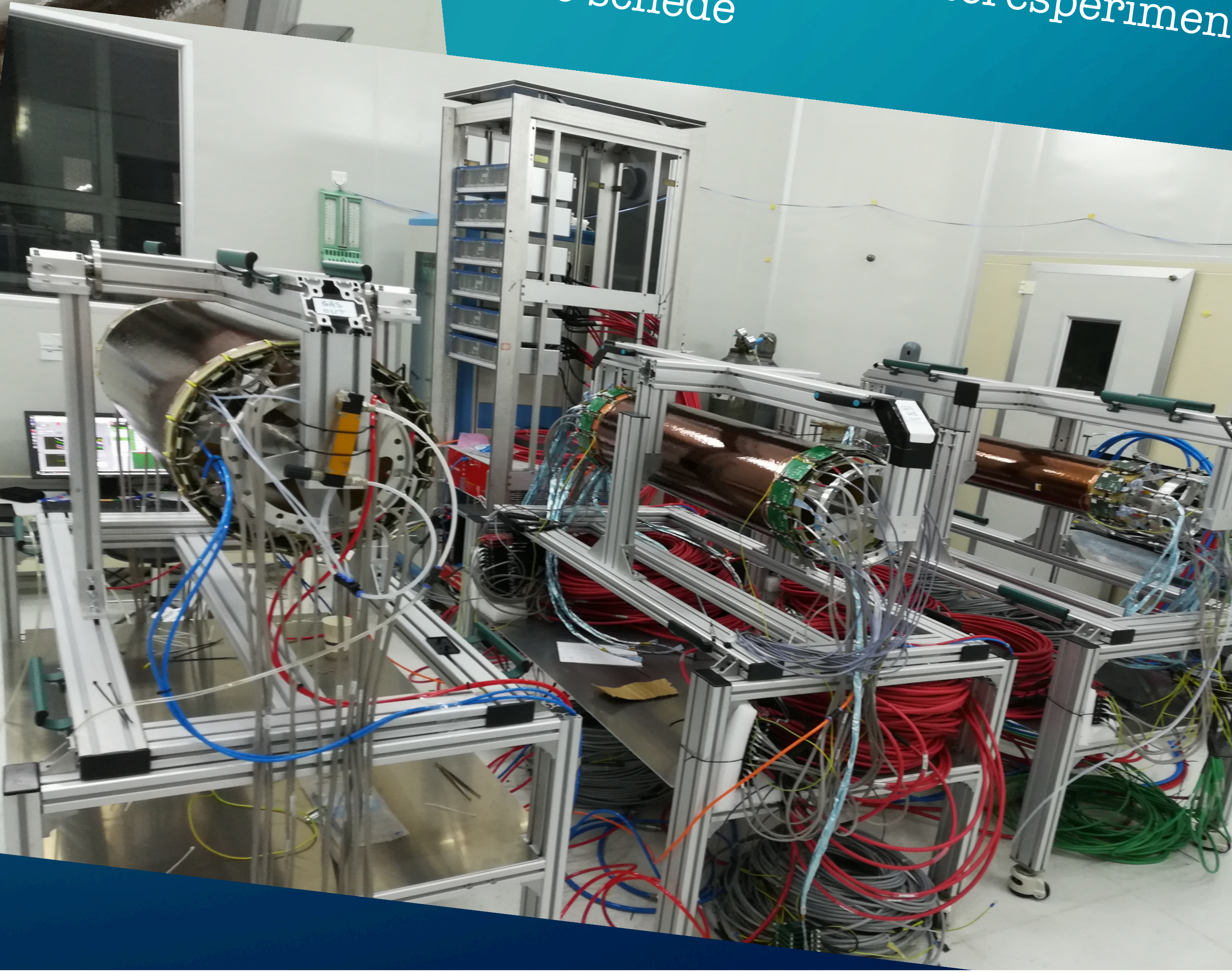


BESIII

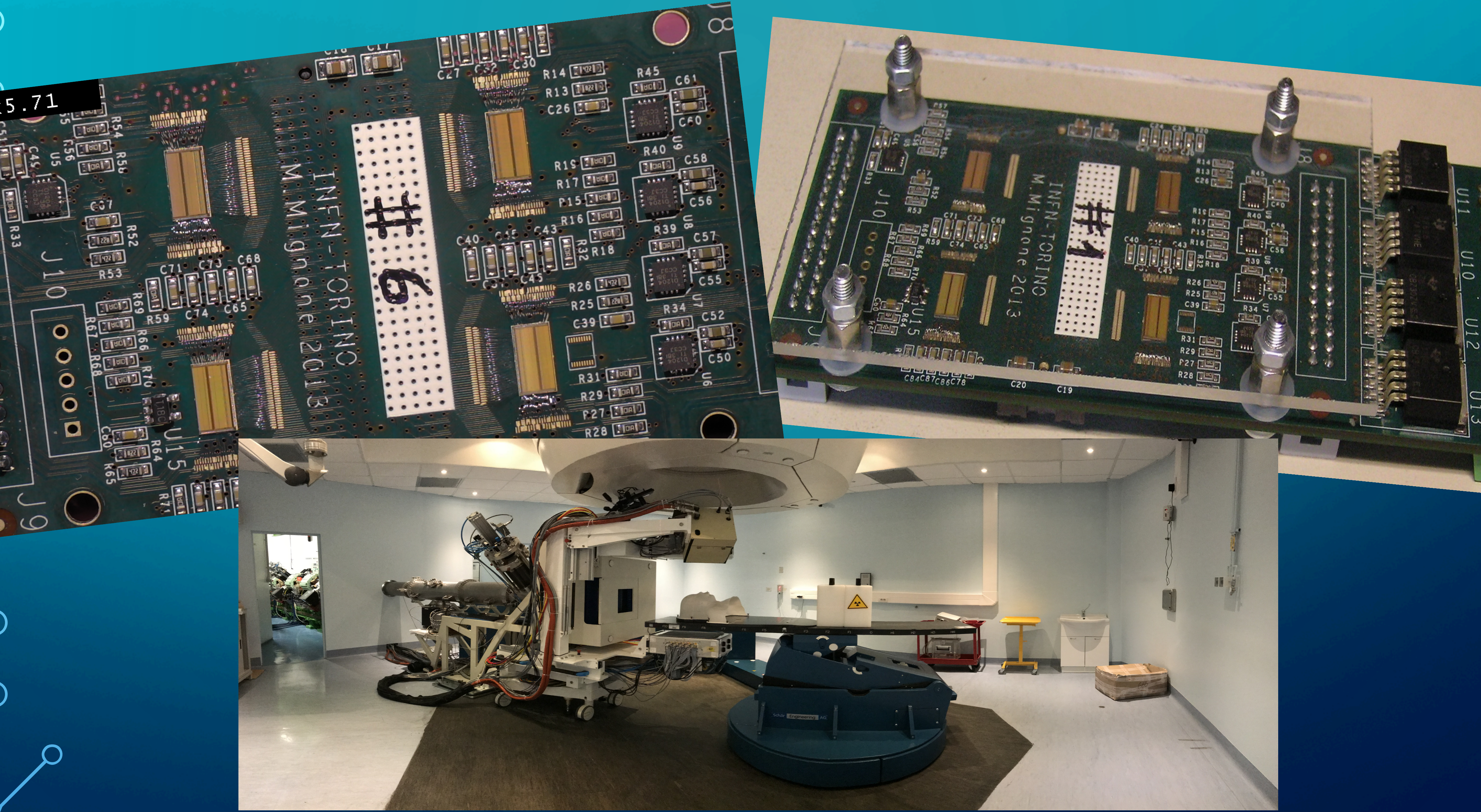


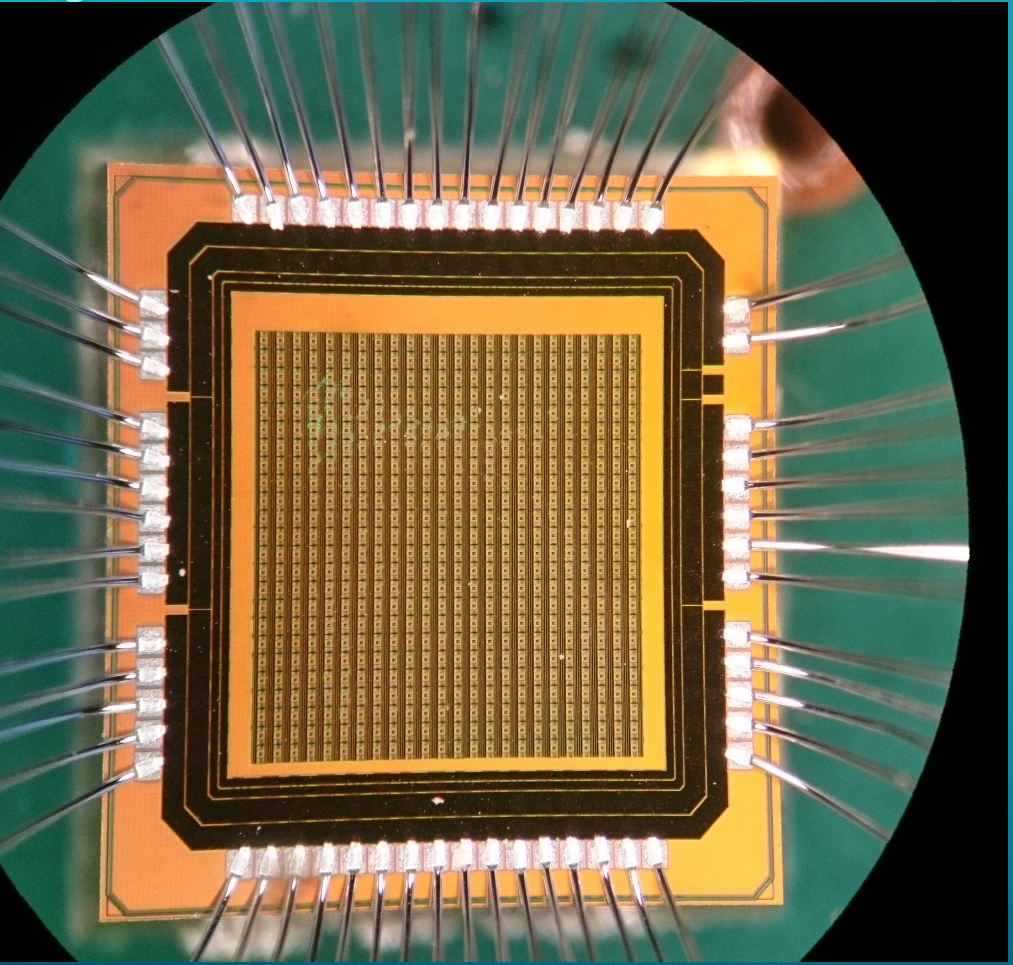
schede montate sul rivelatore

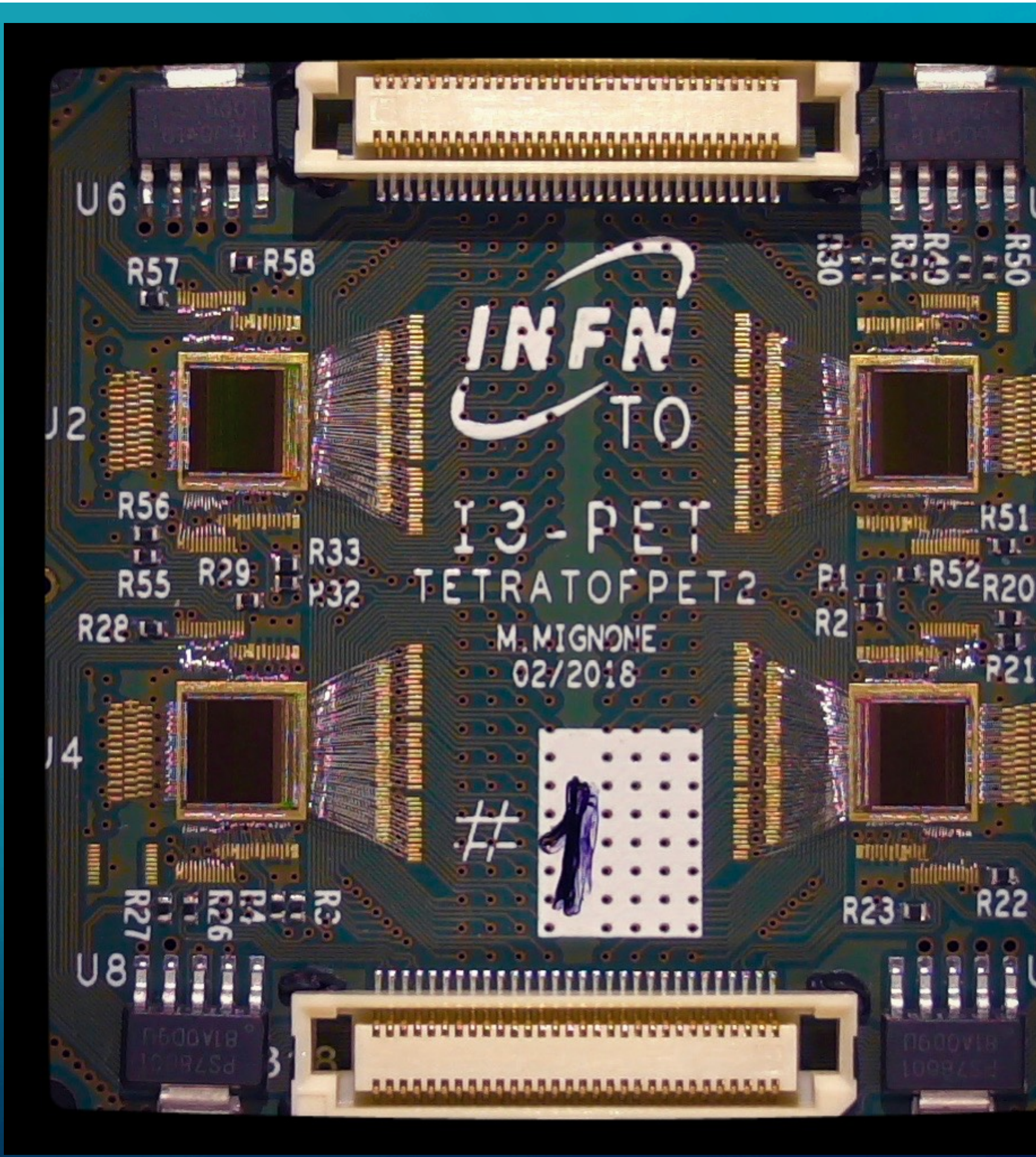
i 3 rivelatori delmontatel'esperimen
con le schede



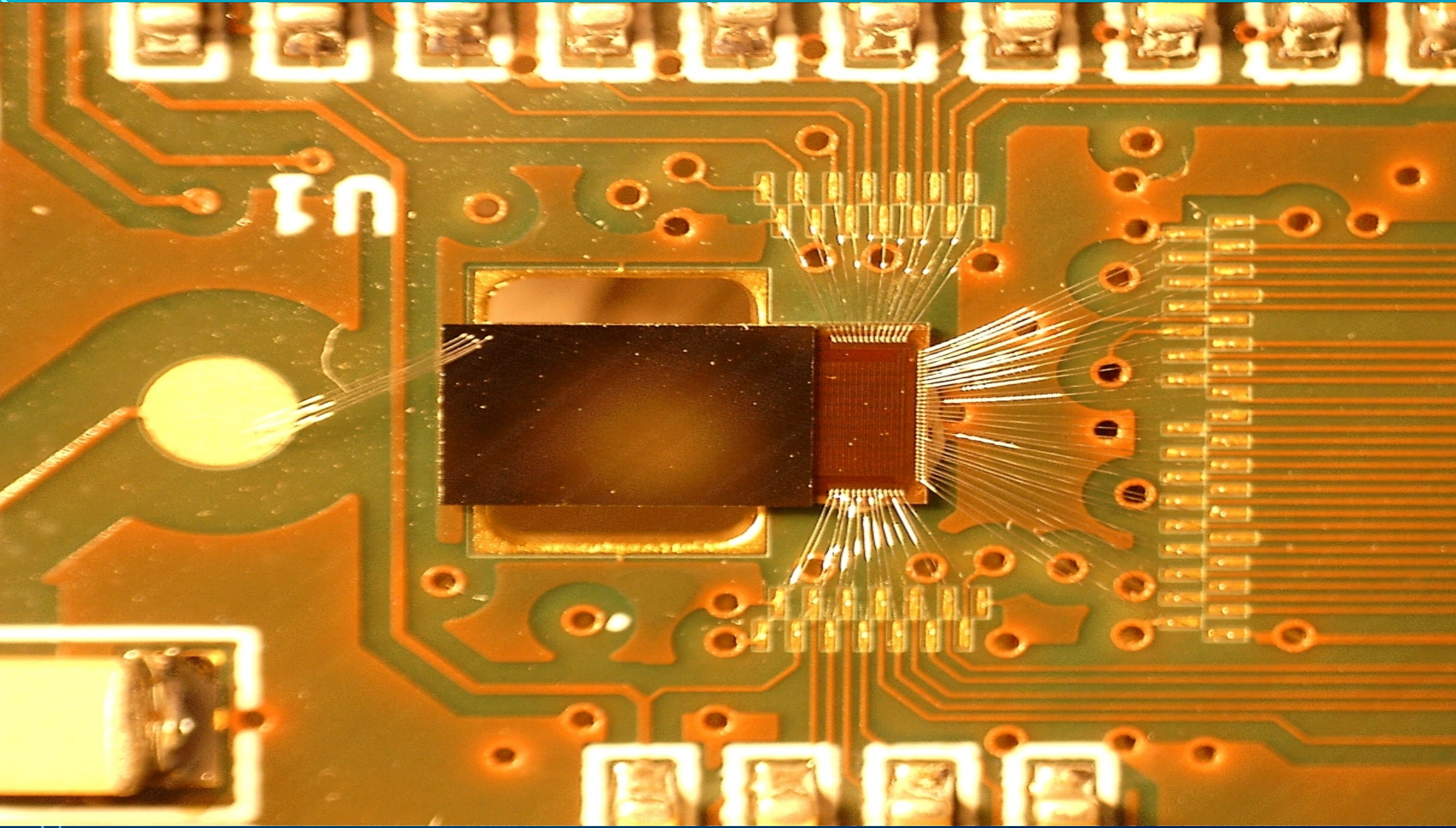
INSIDE -FISICA MEDICA

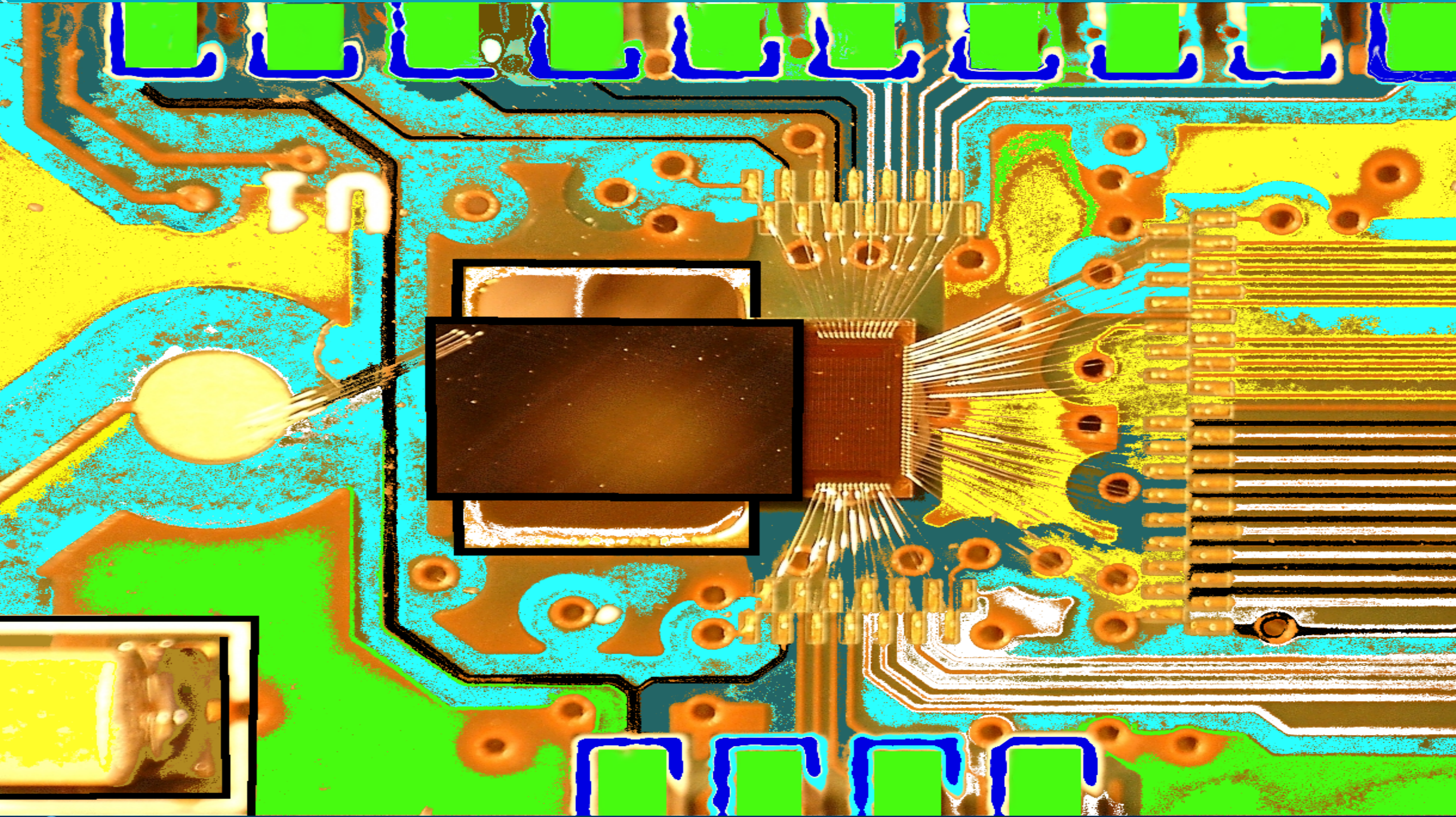


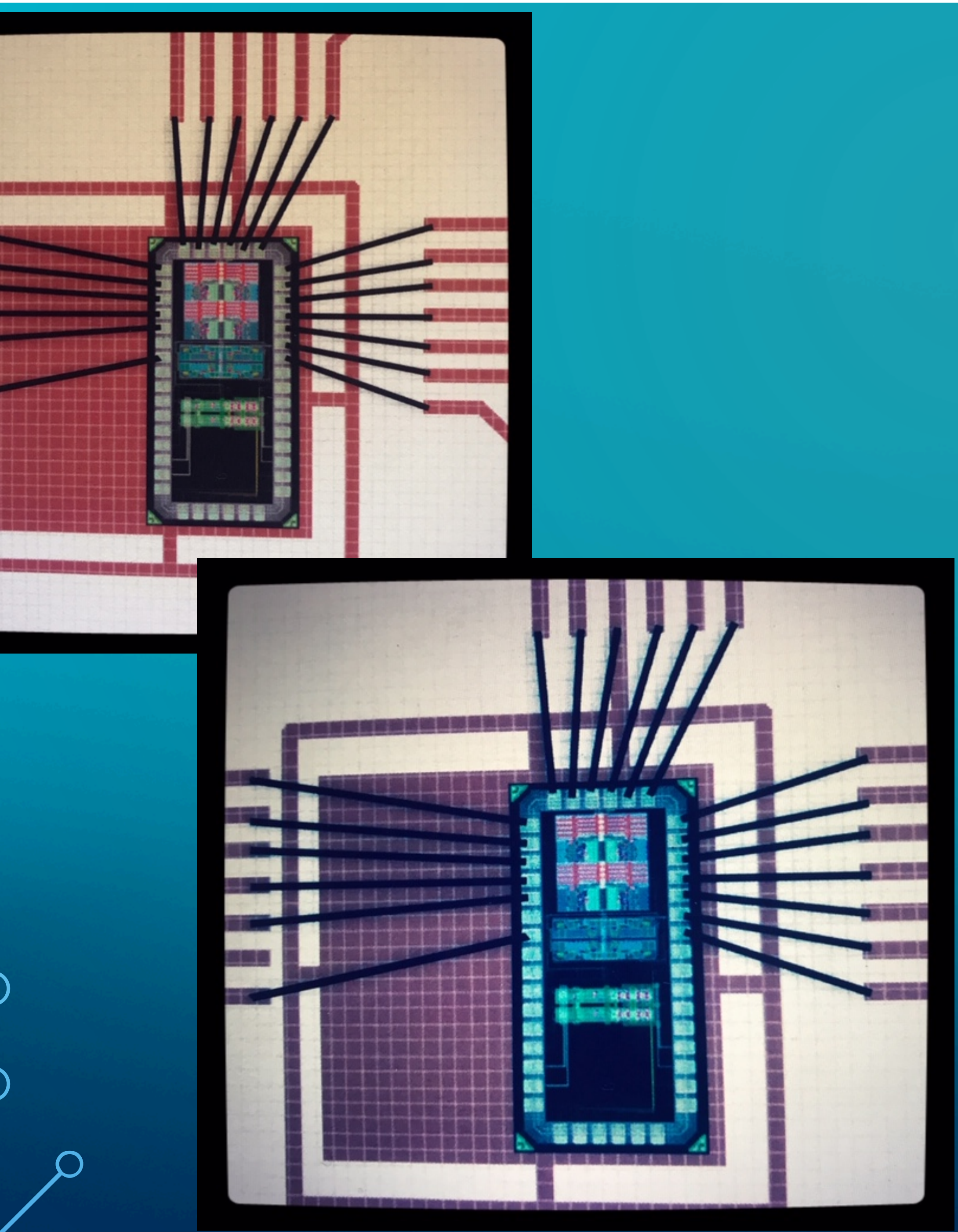


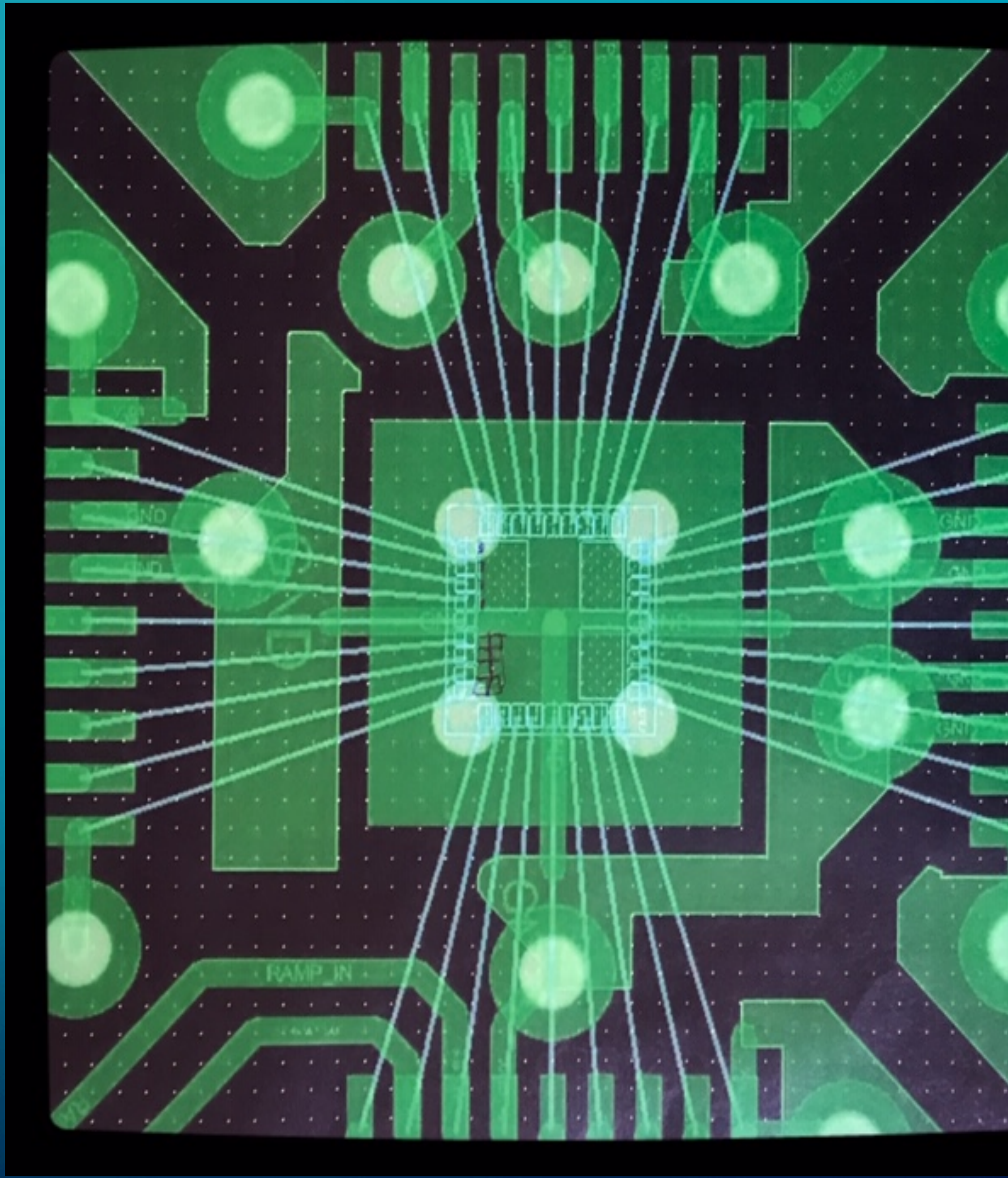


Esempi di bonding


U1






GND
GND
GND
GND
GND
RAMP_IN